High Voltage Power Transistors

DPAK For Surface Mount Applications

Designed for line operated audio output amplifier, $SWITCHMODE^{TM}$ power supply drivers and other switching applications.

Features

- Lead Formed for Surface Mount Applications in Plastic Sleeves (No Suffix)
- Electrically Similar to Popular TIP47, and TIP50
- 250 and 400 V (Min) V_{CEO(sus)}
- 1 A Rated Collector Current
- Epoxy Meets UL 94 V-0 @ 0.125 in
- ESD Ratings: Human Body Model, 3B > 8000 VMachine Model, C > 400 V
- Pb-Free Packages are Available

MAXIMUM RATINGS

Rating	Symbol	Max	Unit
Collector-Emitter Voltage MJD47 MJD50	V _{CEO}	250 400	Vdc
Collector-Base Voltage MJD47 MJD50	V _{CB}	350 500	Vdc
Emitter-Base Voltage	V _{EB}	5	Vdc
Collector Current - Continuous - Peak	I _C	1 2	Adc
Base Current	Ι _Β	0.6	mAdc
Total Power Dissipation @ T _C = 25°C Derate above 25°C	P _D	15 0.12	W W/°C
Total Power Dissipation (Note 1) @ T _A = 25°C Derate above 25°C	P _D	1.56 0.0125	W W/°C
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-65 to +150	°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance Junction-to-Case	$R_{ heta JC}$	8.33	°C/W
Thermal Resistance Junction-to-Ambient (Note 1)	$R_{\theta JA}$	80	°C/W
Lead Temperature for Soldering Purpose	Tı	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

 These ratings are applicable when surface mounted on the minimum pad sizes recommended.



ON Semiconductor®

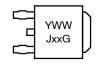
http://onsemi.com

NPN SILICON POWER TRANSISTORS 1 AMPERE 250, 400 VOLTS, 15 WATTS



DPAK CASE 369C STYLE 1

MARKING DIAGRAM



Y = Year

WW = Work Week

Jxx = Device Code

xx = 47 or 50

G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Max	Unit
OFF CHARACTERISTICS					
Collector–Emitter Sustaining Voltage (Note 2) $(I_C=30 \text{ mAdc}, I_B=0)$	MJD47 MJD50	V _{CEO(sus)}	250 400	1 1	Vdc
Collector Cutoff Current $(V_{CE} = 150 \text{ Vdc}, I_B = 0)$ $(V_{CE} = 300 \text{ Vdc}, I_B = 0)$	MJD47 MJD50	I _{CEO}		0.2 0.2	mAdc
Collector Cutoff Current $(V_{CE} = 350 \text{ Vdc}, V_{BE} = 0)$ $(V_{CE} = 500 \text{ Vdc}, V_{BE} = 0)$	MJD47 MJD50	I _{CES}	-	0.1 0.1	mAdc
Emitter Cutoff Current (V _{BE} = 5 Vdc, I _C = 0)		I _{EBO}	-	1	mAdc
ON CHARACTERISTICS (Note 2)					
DC Current Gain		h _{FE}	30 10	150 -	-
Collector–Emitter Saturation Voltage (I _C = 1 Adc, I _B = 0.2 Adc)		V _{CE(sat)}	-	1	Vdc
Base-Emitter On Voltage (I _C = 1 Adc, V _{CE} = 10 Vdc)		V _{BE(on)}	ı	1.5	Vdc
DYNAMIC CHARACTERISTICS					
Current Gain — Bandwidth Product (I _C = 0.2 Adc, V _{CE} = 10 Vdc, f = 2 MHz)		f _T	10	-	MHz
Small-Signal Current Gain (I _C = 0.2 Adc, V _{CE} = 10 Vdc, f = 1 kHz)		h _{fe}	25	=	_

^{2.} Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.

TYPICAL CHARACTERISTICS

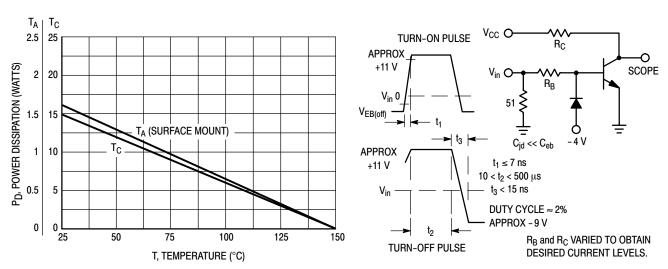
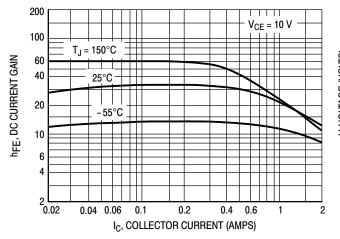


Figure 1. Power Derating

Figure 2. Switching Time Equivalent Circuit



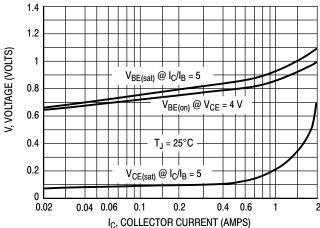


Figure 3. DC Current Gain

Figure 4. "On" Voltages

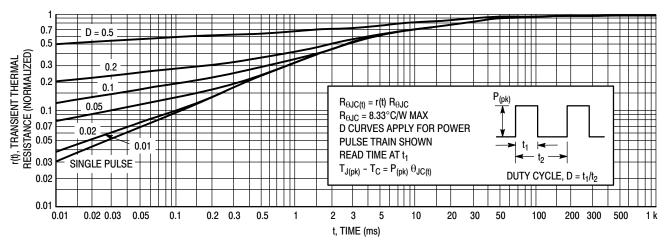


Figure 5. Thermal Response

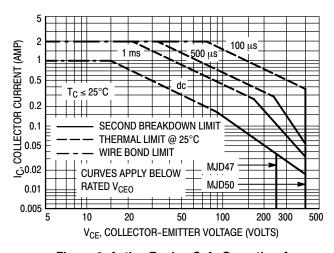


Figure 6. Active Region Safe Operating Area

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate I_C – V_{CE} limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 6 is based on $T_{J(pk)} = 150^{\circ} C$; T_{C} is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided $T_{J(pk)} \le 150^{\circ} C$. $T_{J(pk)}$ may be calculated from the data in Figure 5. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

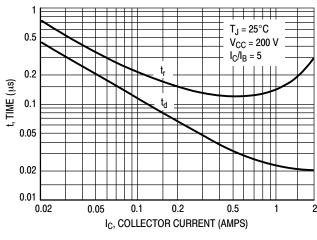


Figure 7. Turn-On Time

Figure 8. Turn-Off Time

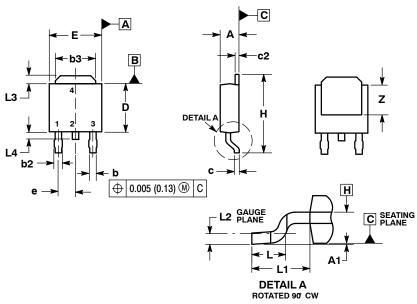
ORDERING INFORMATION

Device	Package	Shipping [†]
MJD47	369C	
MJD47G	369C (Pb-Free)	75 Units / Rail
MJD47T4	369C	
MJD47T4G	369C (Pb-Free)	2500 / Tape & Reel
MJD50	369C	
MJD50G	369C (Pb-Free)	75 Units / Rail
MJD50T4	369C	
MJD50T4G	369C (Pb-Free)	2500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

DPAK CASE 369C-01 ISSUE D



NOTES:

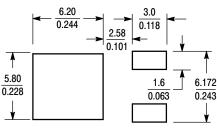
- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994
- 2. CONTROLLING DIMENSION: INCHES.
- 2. CONTROLLING DIMENSION: INCHES.
 3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.
 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
- DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
- 6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.086	0.094	2.18	2.38	
A1	0.000	0.005	0.00	0.13	
b	0.025	0.035	0.63	0.89	
b2	0.030	0.045	0.76	1.14	
b3	0.180	0.215	4.57	5.46	
С	0.018	0.024	0.46	0.61	
c2	0.018	0.024	0.46	0.61	
D	0.235	0.245	5.97	6.22	
E	0.250	0.265	6.35	6.73	
е	0.090	BSC	2.29 BSC		
Н	0.370	0.410	9.40	10.41	
L	0.055	0.070	1.40	1.78	
L1	0.108 REF		2.74 REF		
L2	0.020 BSC		0.51 BSC		
L3	0.035	0.050	0.89	1.27	
L4		0.040		1.01	
Z	0.155		3.93		

STYLE 1:

PIN 1. BASE 2. COLLECTOR 3. EMITTER
4. COLLECTOR

SOLDERING FOOTPRINT*



(mm inches SCALE 3:1

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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